# RENESAS 19-Output DB1900Z Low-Power Derivative with 85ohm Terminations

DATASHEET

### **General Description**

The 9ZXL1950 is a DB1900Z derivative buffer utilizing Low-Power HCSL (LP-HCSL) outputs to increase edge rates on long traces, reduce board space, and reduce power consumption more than 50% from the original 9ZX21901.It is pin-compatible to the 9ZXL1930 and fully integrates the output terminations. It is suitable for PCI-Express Gen1/2/3 or QPI/UPI applications, and uses a fixed external feedback to maintain low drift for demanding QPI/UPI applications.

### **Recommended Application**

Buffer for Romley, Grantley and Purley Servers

### **Output Features**

19 LP-HCSL output pairs w/integrated terminations (Zo =  $85\Omega$ )

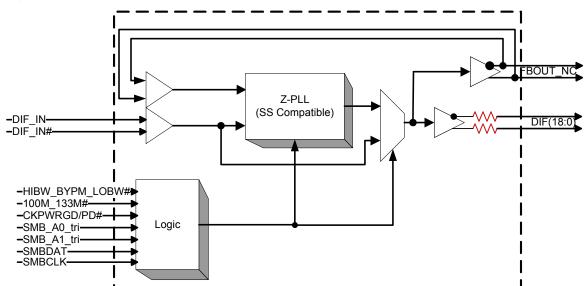
### **Key Specifications**

- Cycle-to-cycle jitter: <50ps
- Output-to-output skew: <50ps
- Input-to-output delay variation: <50ps</li>
- Phase jitter: PCle Gen3 <1ps rms</li>
- Phase jitter: QPI/UPI 9.6GB/s <0.2ps rms

#### Features/Benefits

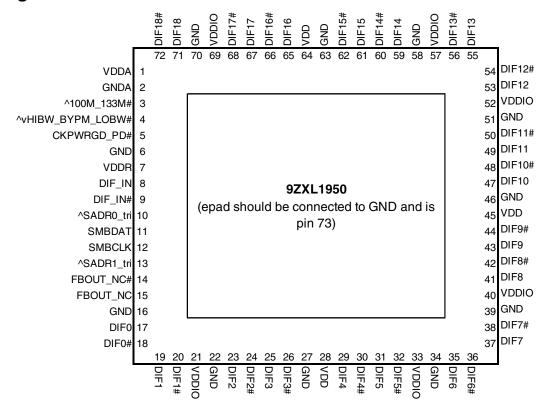
- LP-HCSL outputs; up to 90% IO power reduction, better signal integrity over long traces
- Direct connect to 85Ω transmission lines; eliminates 76 termination resistors, saves 130mm<sup>2</sup> area
- Pin compatible to the 9ZXL1930; easy upgrade to reduced board space
- 72-pin VFQFPN package; smallest 19-output Z-buffer
- Fixed feedback path; ~0ps input-to-output delay
- 9 Selectable SMBus addresses; multiple devices can share same SMBus segment
- Separate VDDIO for outputs; allows maximum power savings
- PLL or bypass mode; PLL can dejitter incoming clock
- 100MHz & 133.33MHz PLL mode; legacy QPI support
- Selectable PLL BW; minimizes jitter peaking in downstream PLL's
- Spread spectrum compatible; tracks spreading input clock for EMI reduction
- SMBus Interface; unused outputs can be disabled

### **Block Diagram**





### **Pin Configuration**



Note: Pins with ^ prefix have internal 120K pullup
Pins with v prefix have internal 120K pulldowm
Pins with ^v prefix have internal 120K pullup/pulldown (biased to VDD/2)

#### **Power Management Table**

Inputs	<b>Control Bits</b>	O	Outputs		
CKPWRGD_PD#	DIF_IN/ DIF_IN#	SMBus EN bit	DIFx/ DIFx#	FBOUT_NC/ FB_OUT_NC#	PLL State
0	Χ	Х	Low/Low	Low/Low	OFF
		0	Low/Low	Running	ON
1	Running	1	Running	Running	ON

#### **Power Connections**

	Description		
VDD	VDDIO	GND	Description
1		2	Analog PLL
7		6	Analog Input
28, 45, 64	21, 33, 40, 52, 57, 69	16, 22, 27, 34, 39, 46, 51, 58, 63, 70, 73	DIF clocks

#### Functionality at Power-up (PLL mode)

100M 133M#	DIF_IN	DIFx
100W_100W#	(MHz)	(MHz)
1	100.00	DIF_IN
0	133.33	DIF IN

#### **PLL Operating Mode**

HiBW_BypM_LoBW#	Byte0, bit (7:6)
Low ( PLL Low BW)	00
Mid (Bypass)	01
High (PLL High BW)	11

NOTE: PLL is off in Bypass mode

#### **Tri-level Input Thresholds**

Level	Voltage
Low	<0.8V
Mid	1.2 <vin<1.8v< td=""></vin<1.8v<>
High	Vin > 2.2V



# **Pin Descriptions**

PIN#	PIN NAME	PIN TYPE	DESCRIPTION
1	VDDA	PWR	Power for the PLL core.
2	GNDA	GND	Ground pin for the PLL core.
3	^100M_133M#	IN	3.3V Input to select operating frequency. This pin has an internal pull-up resistor.  See Functionality Table for Definition
4	^vHIBW_BYPM_LOBW#	LATCHE D IN	Trilevel input to select High BW, Bypass or Low BW mode. See PLL Operating Mode Table for Details.
5	CKPWRGD_PD#	IN	3.3V Input notifies device to sample latched inputs and start up on first high assertion, or exit Power Down Mode on subsequent assertions. Low enters Power Down Mode.
6	GND	GND	Ground pin.
7	VDDR	PWR	3.3V power for differential input clock (receiver). This VDD should be treated as an analog power rail and filtered appropriately.
8	DIF_IN	IN	HCSL True input
9	DIF_IN#	IN	HCSL Complementary Input
10	^SADR0_tri	IN	SMBus address bit. This is a tri-level input that works in conjunction with the SADR1 to decode 1 of 9 SMBus Addresses. It has an internal 120Kohm pull up resistor.
11	SMBDAT	I/O	Data pin of SMBUS circuitry, 5V tolerant
12	SMBCLK	IN	Clock pin of SMBUS circuitry, 5V tolerant
13	^SADR1_tri	IN	SMBus address bit. This is a tri-level input that works in conjunction with the SADR0 to decode 1 of 9 SMBus Addresses. It has an internal 120Kohm pull up resistor.
14	FBOUT_NC#	OUT	Complementary half of differential feedback output. This pin should NOT be connected to anything outside the chip. It exists to provide delay path matching to get 0 propagation delay.
15	FBOUT_NC	ОПТ	True half of differential feedback output. This pin should NOT be connected to anything outside the chip. It exists to provide delay path matching to get 0 propagation delay.
16	GND	GND	Ground pin.
17	DIF0	OUT	Differential true clock output
18	DIF0#	OUT	Differential Complementary clock output
19	DIF1	OUT	Differential true clock output
20	DIF1#	OUT	Differential Complementary clock output
21	VDDIO	PWR	Power supply for differential outputs
22	GND	GND	Ground pin.
23	DIF2	OUT	Differential true clock output
24	DIF2#	OUT	Differential Complementary clock output
25	DIF3	OUT	Differential true clock output
26	DIF3#	OUT	Differential Complementary clock output
27	GND	GND	Ground pin.
28	VDD	PWR	Power supply, nominal 3.3V
29	DIF4	OUT	Differential true clock output
30	DIF4#	OUT	Differential Complementary clock output
31	DIF5	OUT	Differential true clock output
32	DIF5#	OUT	Differential Complementary clock output
33	VDDIO	PWR	Power supply for differential outputs
34	GND	GND	Ground pin.
35	DIF6	OUT	Differential true clock output
36	DIF6#	OUT	Differential Complementary clock output



# Pin Descriptions (cont.)

PIN#	PIN NAME	PIN TYPE	DESCRIPTION
37	DIF7	OUT	Differential true clock output
38	DIF7#	OUT	Differential Complementary clock output
39	GND	GND	Ground pin.
40	VDDIO	PWR	Power supply for differential outputs
41	DIF8	OUT	Differential true clock output
42	DIF8#	OUT	Differential Complementary clock output
43	DIF9	OUT	Differential true clock output
44	DIF9#	OUT	Differential Complementary clock output
45	VDD	PWR	Power supply, nominal 3.3V
46	GND	GND	Ground pin.
47	DIF10	OUT	Differential true clock output
48	DIF10#	OUT	Differential Complementary clock output
49	DIF11	OUT	Differential true clock output
50	DIF11#	OUT	Differential Complementary clock output
51	GND	GND	Ground pin.
52	VDDIO	PWR	Power supply for differential outputs
53	DIF12	OUT	Differential true clock output
54	DIF12#	OUT	Differential Complementary clock output
55	DIF13	OUT	Differential true clock output
56	DIF13#	OUT	Differential Complementary clock output
57	VDDIO	PWR	Power supply for differential outputs
58	GND	GND	Ground pin.
59	DIF14	OUT	Differential true clock output
60	DIF14#	OUT	Differential Complementary clock output
61	DIF15	OUT	Differential true clock output
62	DIF15#	OUT	Differential Complementary clock output
63	GND	GND	Ground pin.
64	VDD	PWR	Power supply, nominal 3.3V
65	DIF16	OUT	Differential true clock output
66	DIF16#	OUT	Differential Complementary clock output
67	DIF17	OUT	Differential true clock output
68	DIF17#	OUT	Differential Complementary clock output
69	VDDIO	PWR	Power supply for differential outputs
70	GND	GND	Ground pin.
71	DIF18	OUT	Differential true clock output
72	DIF18#	OUT	Differential Complementary clock output
73	epad	GND	Connect EPAD to ground.



### **Electrical Characteristics-Absolute Maximum Ratings**

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
3.3V Core Supply Voltage	VDDA, R				4.6	V	1,2
3.3V Logic Supply Voltage	VDD				4.6	V	1,2
I/O Supply Voltage	VDDIO				4.6	V	1,2
Input Low Voltage	$V_{IL}$		GND-0.5			V	1
Input High Voltage	$V_{IH}$	Except for SMBus interface			V <sub>DD</sub> +0.5V	V	1
Input High Voltage	V <sub>IHSMB</sub>	SMBus clock and data pins			5.5V	V	1
Storage Temperature	Ts		-65		150	°C	1
Junction Temperature	Tj				125	°C	1
Input ESD protection	ESD prot	Human Body Model	2000			V	1

<sup>&</sup>lt;sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

### **Electrical Characteristics-DIF\_IN Clock Input Parameters**

TA = T<sub>COM</sub>; Supply Voltage VDD/VDDA = 3.3 V +/-5%, VDDIO = 1.05 to 3.3 V +/-5%. See Test Loads for Loading Conditions

7. COM, Cappy tollage 122, 122.1 Clot 1, 6,6, 122.0 Hos to clot 1, 6,61 Co 1 Cot 2000 Hos 200								
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES	
Input Crossover Voltage - DIF_IN	V <sub>CROSS</sub>	Cross Over Voltage	150		900	mV	1	
Input Swing - DIF_IN	V <sub>SWING</sub>	Differential value	300			mV	1	
Input Slew Rate - DIF_IN	dv/dt	Measured differentially	0.4		8	V/ns	1,2	
Input Leakage Current	I <sub>IN</sub>	$V_{IN} = V_{DD}$ , $V_{IN} = GND$	-5		5	uA		
Input Duty Cycle	d <sub>tin</sub>	Measurement from differential wavefrom	45		55	%	1	
Input Jitter - Cycle to Cycle	$J_{DIFIn}$	Differential Measurement	0		125	ps	1	

<sup>&</sup>lt;sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

### **Electrical Characteristics-Current Consumption**

TA = T<sub>COM</sub>; Supply Voltage VDD/VDDA = 3.3 V +/-5%, VDDIO = 1.05 to 3.3V +/-5%. See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
	I <sub>DDVDD</sub>	All outputs 100MHz, $C_L = 2pF$ ; $Zo = 85\Omega$		20	35	mA	
Operating Supply Current	I <sub>DDVDDA/R</sub>	All outputs 100MHz, $C_L = 2pF$ ; $Zo = 85\Omega$		15	20	mA	
	I <sub>DDVDDIO</sub>	All outputs 100MHz, $C_L = 2pF$ ; $Zo = 85\Omega$		142	185	mA	
	I <sub>DDVDDPD</sub>	All differential pairs low-low		2.2	6	mA	
Powerdown Current	I <sub>DDVDDA/RPD</sub>	All differential pairs low-low		4.5	9	mA	
	I <sub>DDVDDIOPD</sub>	All differential pairs low-low		0.1	1	mA	·

<sup>&</sup>lt;sup>2</sup> Operation under these conditions is neither implied nor guaranteed.

<sup>&</sup>lt;sup>2</sup>Slew rate measured through +/-75mV window centered around differential zero



### **Electrical Characteristics-Input/Supply/Common Output Parameters**

TA = T<sub>COM</sub>; Supply Voltage VDD/VDDA = 3.3 V +/-5%, VDDIO = 1.05 to 3.3V +/-5%. See Test Loads for Loading Conditions

IA - ICOM, Supply Voltage V	100/100A -	= 3.3  V  +/-3/6,  VDDIO = 1.03  to  3.3  V  +/-3/6.  See I	est Luaus i	or Loading	Conditions		
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Ambient Operating Temperature	ТСОМ	Commmercial range	0	35	70	°C	
Input High Voltage	V <sub>IH</sub>	Single-ended inputs, except SMBus, low threshold and tri-level inputs	2		V <sub>DD</sub> + 0.3	٧	
Input Low Voltage	$V_{IL}$	Single-ended inputs, except SMBus, low threshold and tri-level inputs	GND - 0.3		0.8	>	
	I <sub>IN</sub>	Single-ended inputs, $V_{IN} = GND$ , $V_{IN} = VDD$	-5		5	uA	
Input Current	I <sub>INP</sub>	$\label{eq:single-ended} Single-ended inputs \\ V_{IN} = 0 \ V; \ Inputs \ with internal pull-up resistors \\ V_{IN} = VDD; \ Inputs \ with internal pull-down resistors$	-200		200	uA	
	$F_{ibyp}$	V <sub>DD</sub> = 3.3 V, Bypass mode	33		150	MHz	2
Input Frequency	$F_{ipII}$	$V_{DD} = 3.3 \text{ V}, 100\text{MHz PLL mode}$	90	100.00	110	MHz	2
	$F_{ipII}$	V <sub>DD</sub> = 3.3 V, 133.33MHz PLL mode	120	133.33	147	MHz	2
Pin Inductance	$L_{pin}$				7	nΗ	1
	$C_{IN}$	Logic Inputs, except DIF_IN	1.5		5	pF	1
Capacitance	C <sub>INDIF_IN</sub>	DIF_IN differential clock inputs	1.5		2.7	рF	1,4
	C <sub>OUT</sub>	Output pin capacitance			6	pF pF pF ms	1
Clk Stabilization	T <sub>STAB</sub>	From V <sub>DD</sub> Power-Up and after input clock stabilization or de-assertion of PD# to 1st clock		0.65	1	ms	2
Input SS Modulation Frequency	f <sub>MODIN</sub>	Allowable Frequency (Triangular Modulation)	30	31.5	33	kHz	
Tdrive_PD#	t <sub>DRVPD</sub>	DIF output enable after PD# de-assertion		25	300	us	1,3
Tfall	$t_{F}$	Fall time of control inputs			5	ns	1,2
Trise	t <sub>R</sub>	Rise time of control inputs			5	ns	1,2
SMBus Input Low Voltage	$V_{ILSMB}$				0.8	V	
SMBus Input High Voltage	$V_{IHSMB}$		2.1		$V_{DDSMB}$	٧	
SMBus Output Low Voltage	$V_{OLSMB}$	@ I <sub>PULLUP</sub>			0.4	٧	
SMBus Sink Current	I <sub>PULLUP</sub>	@ V <sub>OL</sub>	4			mA	
Nominal Bus Voltage	$V_{\text{DDSMB}}$	3V to 5V +/- 10%	2.7		5.5	V	
SCLK/SDATA Rise Time	t <sub>RSMB</sub>	(Max VIL - 0.15) to (Min VIH + 0.15)			1000	ns	1
SCLK/SDATA Fall Time	t <sub>FSMB</sub>	(Min VIH + 0.15) to (Max VIL - 0.15)			300	ns	1
SMBus Operating Frequency	f <sub>SMB</sub>	SMBus operating frequency	100			kHz	5
SCLK/SDATA Rise Time SCLK/SDATA Fall Time SMBus Operating	t <sub>RSMB</sub> t <sub>FSMB</sub>	(Max VIL - 0.15) to (Min VIH + 0.15) (Min VIH + 0.15) to (Max VIL - 0.15)			1000	ns ns	1

<sup>&</sup>lt;sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.

<sup>&</sup>lt;sup>2</sup>Control input must be monotonic from 20% to 80% of input swing.

<sup>&</sup>lt;sup>3</sup>Time from deassertion until outputs are >200 mV

<sup>&</sup>lt;sup>4</sup>DIF\_IN input

<sup>&</sup>lt;sup>5</sup>The differential input clock must be running for the SMBus to be active



### Electrical Characteristics-DIF 0.7V Low Power Differential Outputs

TA = T<sub>COM</sub>; Supply Voltage VDD/VDDA = 3.3 V +/-5%, VDDIO = 1.05 to 3.3V +/-5%. See Test Loads for Loading Conditions

		·					
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
Slew rate	Trf	Scope averaging on	1.5	2.7	4	V/ns	1, 2, 3
Slew rate matching	ΔTrf	Slew rate matching.		8.8	20	%	1, 2, 4
Voltage High	VHigh	Statistical measurement on single-ended signal using oscilloscope math function. (Scope	660	787	850	mV	
Voltage Low	VLow	averaging on)		33	150	""	
Max Voltage	Vmax	Single ended signal using absolute value.		845	1150	mV	
Min Voltage	Vmin	Includes 300mV of over/undershoot. (Scope	-300	9		IIIV	
Crossing Voltage (abs)	Vcross_abs	Scope averaging off	250	471	550	mV	1, 5
Crossing Voltage (var)	Δ-Vcross	Scope averaging off		14	140	mV	1, 6

<sup>&</sup>lt;sup>1</sup>Guaranteed by design and characterization, not 100% tested in production.  $C_L = 2pF$  with  $Z_0 = 85\Omega$  differential trace impedance.

### **Clock Periods–Differential Outputs with Spread Spectrum Disabled**

		Measurement Window								
	Contor	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
SSC OFF	Center Freq. MHz	-c2c jitter AbsPer Min	-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	Units	Notes
DIF	100.00	9.94900		9.99900	10.00000	10.00100		10.05100	ns	1,2,3
DIF	133.33	7.44925		7.49925	7.50000	7.50075		7.55075	ns	1,2,4

### Clock Periods-Differential Outputs with Spread Spectrum Enabled

		Measurement Window								Notes
SSC ON	Comton	1 Clock	1us	0.1s	0.1s	0.1s	1us	1 Clock		
	Center Freq. MHz	ON Freqc2c jitter		-SSC Short-Term Average Min	- ppm Long-Term Average Min	0 ppm Period Nominal	+ ppm Long-Term Average Max	+SSC Short-Term Average Max	+c2c jitter AbsPer Max	Units
DIF	99.75	9.94906	9.99906	10.02406	10.02506	10.02607	10.05107	10.10107	ns	1,2,3
DIF	133.00	7.44930	7.49930	7.51805	7.51880	7.51955	7.53830	7.58830	ns	1,2,4

#### Notes:

<sup>&</sup>lt;sup>2</sup> Measured from differential waveform

<sup>&</sup>lt;sup>3</sup> Slew rate is measured through the Vswing voltage range centered around differential 0V. This results in a +/-150mV window around differential 0V.

<sup>&</sup>lt;sup>4</sup> Matching applies to rising edge rate for Clock and falling edge rate for Clock#. It is measured using a +/-75mV window centered on the average cross point where Clock rising meets Clock# falling. The median cross point is used to calculate the voltage thresholds the oscilloscope is to use for the edge rate calculations.

<sup>&</sup>lt;sup>5</sup> Vcross is defined as voltage where Clock = Clock# measured on a component test board and only applies to the differential rising edge (i.e. Clock rising and Clock# falling).

<sup>&</sup>lt;sup>6</sup> The total variation of all Vcross measurements in any particular system. Note that this is a subset of Vcross\_min/max (Vcross absolute) allowed. The intent is to limit Vcross induced modulation by setting Δ-Vcross to be smaller than Vcross absolute.

<sup>&</sup>lt;sup>1</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>&</sup>lt;sup>2</sup> All Long Term Accuracy specifications are guaranteed with the assumption that the input clock complies with CK420BQ/CK410B+ accuracy requirements (+/-100ppm). The 9ZXL1950 itself does not contribute to ppm error.

<sup>&</sup>lt;sup>3</sup> Driven by SRC output of main clock, 100 MHz PLL Mode or Bypass mode

<sup>&</sup>lt;sup>4</sup> Driven by CPU output of main clock, 133 MHz PLL Mode or Bypass mode



#### **Electrical Characteristics-Skew and Differential Jitter Parameters**

TA = T<sub>COM</sub>; Supply Voltage VDD/VDDA = 3.3 V +/-5%, VDDIO = 1.05 to 3.3V +/-5%. See Test Loads for Loading Conditions

	0) (1 1 0 0 :	001101710110		T) (D			
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	NOTES
CLK_IN, DIF[x:0]	t <sub>SPO_PLL</sub>	Input-to-Output Skew in PLL mode nominal value @ 35°C, 3.3V, 100MHz	-150	-117	-50	ps	1,2,4,5,8
CLK_IN, DIF[x:0]	t <sub>PD_BYP</sub>	Input-to-Output Skew in Bypass mode nominal value @ 35°C, 3.3V	2.5	3.6	4.5	ns	1,2,3,5,8
CLK_IN, DIF[x:0]	t <sub>DSPO_PLL</sub>	Input-to-Output Skew Varation in PLL mode across voltage and temperature	-50	0	50	ps	1,2,3,5,8
CLK_IN, DIF[x:0]	t <sub>DSPO_BYP</sub>	Input-to-Output Skew Varation in Bypass mode across temperature for a given voltage	-250	0	250	ps	1,2,3,5,8
CLK_IN, DIF[x:0]	t <sub>DTE</sub>	Random Differential Tracking error beween two 9ZX devices in Hi BW Mode		1	5	ps (rms)	1,2,3,5,8
CLK_IN, DIF[x:0]	t <sub>DSSTE</sub>	Random Differential Spread Spectrum Tracking error beween two 9ZX devices in Hi BW Mode		5	75	ps	1,2,3,5,8
DIF[x:0]	t <sub>SKEW_ALL</sub>	Output-to-Output Skew across all outputs (Common to Bypass and PLL mode). 100MHz		37	50	ps	1,2,3,8
PLL Jitter Peaking	j peak-hibw	LOBW#_BYPASS_HIBW = 1	0	1.8	2.5	dB	7,8
PLL Jitter Peaking	jpeak-lobw	LOBW#_BYPASS_HIBW = 0	0	0.7	2	dB	7,8
PLL Bandwidth	pll <sub>HIBW</sub>	LOBW#_BYPASS_HIBW = 1	2	3.3	4	MHz	8,9
PLL Bandwidth	pll <sub>LOBW</sub>	LOBW#_BYPASS_HIBW = 0	0.7	1.2	1.4	MHz	8,9
Duty Cycle	t <sub>DC</sub>	Measured differentially, PLL Mode	45	50	55	%	1
Duty Cycle Distortion	t <sub>DCD</sub>	Measured differentially, Bypass Mode @100MHz	0	0.7	1.5	%	1,10
littor Cycle to cycle	+.	PLL mode		12	50	ps	1,11
Jitter, Cycle to cycle	t <sub>jcyc-cyc</sub>	Additive Jitter in Bypass Mode		0	10	ps	1,11

#### Notes for preceding table:

<sup>&</sup>lt;sup>1</sup> Measured into fixed 2 pF load cap. Input to output skew is measured at the first output edge following the corresponding input.

<sup>&</sup>lt;sup>2</sup> Measured from differential cross-point to differential cross-point. This parameter can be tuned with external feedback path, if present.

<sup>&</sup>lt;sup>3</sup> All Bypass Mode Input-to-Output specs refer to the timing between an input edge and the specific output edge created by it.

<sup>&</sup>lt;sup>4</sup> This parameter is deterministic for a given device

<sup>&</sup>lt;sup>5</sup> Measured with scope averaging on to find mean value.

<sup>&</sup>lt;sup>6.</sup> t is the period of the input clock

<sup>&</sup>lt;sup>7</sup> Measured as maximum pass band gain. At frequencies within the loop BW, highest point of magnification is called PLL jitter peaking.

<sup>&</sup>lt;sup>8.</sup> Guaranteed by design and characterization, not 100% tested in production.

<sup>&</sup>lt;sup>9</sup> Measured at 3 db down or half power point.

<sup>&</sup>lt;sup>10</sup> Duty cycle distortion is the difference in duty cycle between the output and the input clock when the device is operated in bypass mode.

<sup>&</sup>lt;sup>11</sup> Measured from differential waveform



#### **Electrical Characteristics-Phase Jitter Parameters**

 $TA = T_{COM}$ ; Supply Voltage VDD/VDDA = 3.3 V +/-5%, VDDIO = 1.05 to 3.3V +/-5%. See Test Loads for Loading Conditions

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
	t <sub>jphPCleG1</sub>	PCIe Gen 1		34	86	ps (p-p)	1,2,3
	t: L pg: oo	PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		1.2	3	ps (rms)	1,2
	t <sub>jphPCleG2</sub>	PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		2.1	3.1	ps (rms)	1,2
Phase Jitter, PLL Mode	t <sub>jphPCleG3</sub>	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.5	1	ps (rms)	1,2,4
	t <sub>jphQPI_</sub> SMI	QPI & SMI (100MHz or 133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.2	0.5	ps (rms)	1,5
		QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.1	0.3	ps (rms)	1,5
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.1	0.2	ps (rms)	1,5
	t <sub>iphPCleG1</sub>	PCIe Gen 1		0.1	10	ps (p-p)	1,2,3
		PCIe Gen 2 Lo Band 10kHz < f < 1.5MHz		0.1	0.3	ps (rms)	1,2,6
	t <sub>jphPCleG2</sub>	PCIe Gen 2 High Band 1.5MHz < f < Nyquist (50MHz)		0.1	0.7	ps (rms)	1,2,6
Additive Phase Jitter, Bypass mode	t <sub>jphPCleG3</sub>	PCIe Gen 3 (PLL BW of 2-4MHz, CDR = 10MHz)		0.0	0.3	ps (rms)	1,2,4,6
Буразз точе		QPI & SMI (100MHz or 133MHz, 4.8Gb/s, 6.4Gb/s 12UI)		0.0	0.3	ps (rms)	1,5,6
	t <sub>jphQPI_SMI</sub>	QPI & SMI (100MHz, 8.0Gb/s, 12UI)		0.0	0.1	ps (rms)	1,5,6
		QPI & SMI (100MHz, 9.6Gb/s, 12UI)		0.0	0.1	ps (rms)	1,5,6

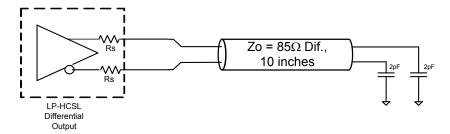
<sup>&</sup>lt;sup>1</sup> Applies to all outputs.

#### **Test Loads**

#### **Differential Output Terminations**

DIF Zo (Ω)	Rs $(\Omega)$
85	Internal
100	7.5
100	(External)

#### 9ZXL Differential Test Loads



<sup>&</sup>lt;sup>2</sup> See http://www.pcisig.com for complete specs

<sup>&</sup>lt;sup>3</sup> Sample size of at least 100K cycles. This figures extrapolates to 108ps pk-pk @ 1M cycles for a BER of 1-12.

<sup>&</sup>lt;sup>4</sup> Subject to final ratification by PCI SIG.

<sup>&</sup>lt;sup>5</sup> Calculated from Intel-supplied Clock Jitter Tool v 1.6.4

<sup>&</sup>lt;sup>6</sup> For RMS figures, additive jitter is calculated by solving the following equation: (Additive jitter)<sup>2</sup> = (total jitter)<sup>2</sup> - (input jitter)<sup>2</sup>



#### **General SMBus Serial Interface Information**

#### **How to Write**

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) sends the byte count = X
- IDT clock will acknowledge
- Controller (host) starts sending Byte N through Byte N+X-1
- IDT clock will acknowledge each byte one at a time
- Controller (host) sends a Stop bit

	Index Blo	ock \	Write Operation
Control	ler (Host)		IDT (Slave/Receiver)
Т	starT bit		
Slave	Address		
WR	WRite		
			ACK
Beginnin	g Byte = N		
			ACK
Data Byte	e Count = X		
			ACK
Beginni	ng Byte N		
			ACK
0		×	
0		X Byte	0
0		.e	0
			0
Byte N	N + X - 1		
			ACK
Р	stoP bit		

#### How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will acknowledge
- Controller (host) sends the beginning byte location = N
- IDT clock will acknowledge
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will acknowledge
- IDT clock will send the data byte count = X
- IDT clock sends Byte N+X-1
- IDT clock sends Byte 0 through Byte X (if X<sub>(H)</sub> was written to Byte 8)
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

	Index Block R	Read C	peration
Co	ntroller (Host)		IDT (Slave/Receiver)
Т	starT bit		
S	ave Address		
WR	WRite		
			ACK
Beg	inning Byte = N		
			ACK
RT	RT Repeat starT		
S	lave Address		
RD	ReaD		
			ACK
			Data Byte Count=X
	ACK		
			Beginning Byte N
	ACK		
		ē	0
	0	X Byte	0
	0	×	0
	0		
			Byte N + X - 1
Ν	Not acknowledge		
Р	stoP bit		



9ZXL1950 SMBus Addressing

SADR(1:0)_tri	SMBus Address (Rd/Wrt bit = 0)
00	D8
OM	DA
01	DE
MO	C2
MM	C4
M1	C6
10	CA
1M	CC
11	CE

SMBusTable: PLL Mode, and Frequency Select Register

Byte	Byte 0 Pin # Name		Pin # Name Control Function		0	1	Default
Bit 7	4	PLL Mode 1	PLL Operating Mode Rd back 1	R	See PLL Operating Mode		Latch
Bit 6	4	PLL Mode 0	PLL Operating Mode Rd back 0	R	Readback Table		Latch
Bit 5	72/71	DIF_18_En	Output Control	RW	Low/Low	Enable	1
Bit 4	68/67	DIF_17_En	Output Control	RW	Low/Low	Enable	1
Bit 3	66/65	DIF_16_En	Output Control	RW	Low/Low	Enable	1
Bit 2		Reserved					
Bit 1		Reserved					
Bit 0	3	100M_133M#	Frequency Select Readback	R	133MHz	100MHz	Latch

SMBusTable: Output Control Register

Byte	1 Pin#	Name	Control Function	Type	0	1	Default
Bit 7	38/37	DIF_7_En	Output Control	RW			1
Bit 6	35/36	DIF_6_En	Output Control	RW			1
Bit 5	31/32	DIF_5_En	5_En Output Control RW		1		
Bit 4	29/30	DIF_4_En	Output Control	RW	Low/Low	Enable	1
Bit 3	25/26	DIF_3_En	Output Control	RW	LOW/LOW		1
Bit 2	23/24	DIF_2_En	Output Control	RW			1
Bit 1	19/20	DIF_1_En	Output Control	RW			1
Bit 0	17/18	DIF_0_En	Output Control	RW			1

SMBusTable: Output Control Register

Byte	2 Pin #	Name	Control Function	Type	0	1	Default
Bit 7	62/61	DIF_15_En	Output Control	RW			1
Bit 6	60/59	DIF_14_En	Output Control	ntrol RW		1	
Bit 5	56/55	DIF_13_En	DIF_13_En Output Control RW		1		
Bit 4	54/53	DIF_12_En	Output Control	RW	Low/Low	Enable	1
Bit 3	50/49	DIF_11_En	Output Control	RW	LOW/LOW		1
Bit 2	48/47	DIF_10_En	Output Control	RW	1		1
Bit 1	44/43	DIF_9_En	Output Control	RW			1
Bit 0	42/41	DIF_8_En	Output Control	RW			1

SMBusTable: PLL SW Override Control Register

Byte	3	Pin#	Name	Control Function	Type	0	1	Default		
Bit 7			Reserved							
Bit 6				Reserved						
Bit 5				Reserved						
Bit 4			Reserved							
Bit 3			PLL_SW_EN	Enable S/W control of PLL BW	RW	HW Latch	SMBus Control	0		
Bit 2			PLL Mode 1	PLL Operating Mode 1	RW	See PLL Op	erating Mode	1		
Bit 1			PLL Mode 0	PLL Operating Mode 1	RW	Readback Table		1		
Bit 0	it 0 Reserved							0		

**Note:** Setting bit 3 to '1' allows the user to overide the Latch value from pin 4 via use of bits 2 and 1. Use the values from the PLL Operating Mode Readback Table. Note that Byte 0, Bits 7:6 will keep the value originally latched on pin 4. A warm reset of the system will have to accomplished if the user changes these bits.



SMBusTable: Reserved Register

Byte	Byte 4 Pin # Name		Name	Control Function	Type	0	1	Default	
Bit 7				Reserved				0	
Bit 6				Reserved				0	
Bit 5				Reserved				0	
Bit 4			Reserved				0		
Bit 3			Reserved				0		
Bit 2			Reserved				0		
Bit 1			Reserved				0		
Bit 0				Reserved					

SMBusTable: Vendor & Revision ID Register

Byte 5	Pin #	Name	Control Function	Type	0	1	Default	
Bit 7		RID3		R	A rov	A rev = 0000		
Bit 6		RID2	REVISION ID  REVISION ID  REVISION ID		Х			
Bit 5	-	RID1			Х			
Bit 4		RID0		R	etc.		Х	
Bit 3		VID3	VENDOR ID	R	-	-	0	
Bit 2		VID2		R	-	-	0	
Bit 1		VID1		R	-	-	0	
Bit 0	-	VID0		R	-	-	1	

SMBusTable: DEVICE ID

Byte 6	Pin #	Name	Control Function	Type	0	1	Default
Bit 7	-	Device ID 7 (MSB)		R			1
Bit 6	-		Device ID 6	R			1
Bit 5	-	Device ID 5		R	1950 is 195 Decimal		0
Bit 4	-		Device ID 4	R	or C	3 Hex	0
Bit 3	-		Device ID 3	R	1550 is 1	55 Decimal	0
Bit 2	-		Device ID 2	R	or 9l	B Hex	0
Bit 1	-		Device ID 1	R			1
Bit 0	-		Device ID 0	R			1

SMBusTable: Byte Count Register

ometation by the countries of the countr								
Byte 7	Pin #	Name	Control Function	Type	0	1	Default	
Bit 7		Reserved				0		
Bit 6			Reserved					
Bit 5		Reserved					0	
Bit 4	-	BC4		RW			0	
Bit 3	-	BC3	Writing to this register configures how	RW	Default value	is 8 hex, so 9	1	
Bit 2	-	BC2	Writing to this register configures how	RW	bytes (0 to 8) v	vill be read back	0	
Bit 1	-	BC1	many bytes will be read back.	RW	by de	efault.	0	
Rit 0	-	BC0	1	RW	1 '		0	

SMBusTable: Reserved Register

Byte	Byte 8 Pin # Name		Name	Control Function	Type	0	1	Default
Bit 7				Reserved				0
Bit 6			Reserved				0	
Bit 5			Reserved				0	
Bit 4			Reserved				0	
Bit 3			Reserved				0	
Bit 2			Reserved				0	
Bit 1			Reserved				0	
Bit 0			Reserved					0



### **Alternate Terminations**

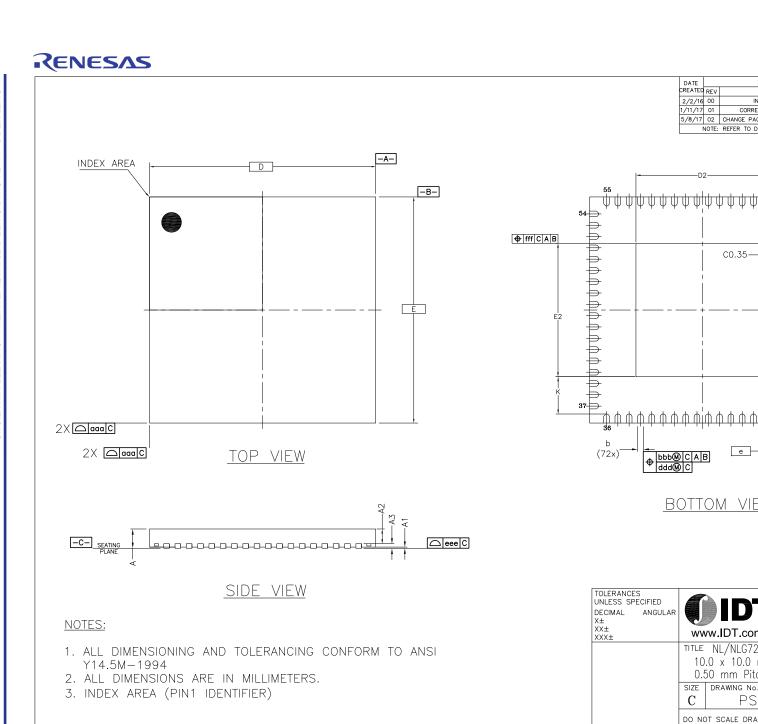
The 9ZXL1950 can be terminated to other logic families. See <u>"AN-891 Driving LVPECL, LVDS, and CML Logic with IDT's "Universal" Low-Power HCSL Outputs"</u> for details.

# **Marking Diagram**



#### Notes:

- 1. "LOT" denotes the lot number.
- 2. "YYWW" is the last two digits of the year and week that the part was assembled.
- 3. "LF" denotes RoHS compliant package.
- 4. Bottom marking: country of origin if not USA.



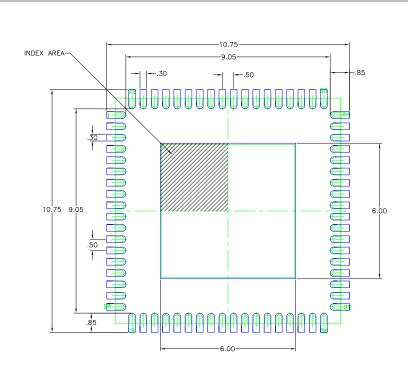
# RENESAS

DATE		
CREATED	REV	
2/2/16		IN.
1/11/17	01	CORRE
5/8/17	02	CHANGE PAG
	NOTE:	REFER TO D

S Y	DI	MENSIO	NS			
S Y M B O L	MIN.	NOM.	MAX.			
D2	5.80	5.90	6.00			
E2	5.80	5.90	6.00			
A2	0.00	0.65	1.00			
L	0.30	0.40	0.50			
А	0.80	0.90	1.00			
A1	0.00	0.02	0.05			
А3		0.20 ref.				
b	0.18	0.25	0.30			
е	0.50 BSC					
D E		10.00 BS				
	1	10.00 BS	<u> </u>			
K		1.65 ref.				
	TOLEF	RANCES				
aaa	0.15					
bbb	0.10					
ccc	0.05					
eee		0.08				
fff		0.10				

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR X± XX± XXX±	ww	w.IDT.com
	10	NL/NLG72 .0 x 10.0 r 50 mm Pitc
	SIZE	DRAWING No.
	DO NO	DT SCALE DRAV

### RENESAS



RECOMMENDED LAND PATTERN DIMENSION

#### NOTES:

- 1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
- 2. TOP DOWN VIEW. AS VIEWED ON PCB.
- 3. COMPONENT OUTLINE SHOWS FOR REFERENCE IN GREEN.
- 4. LAND PATTERN IN BLUE. NSMD PATTERN ASSUMED.
- 5. LAND PATTERN RECOMMENDATION PER IPC-7351B GENERIC REQUIREMENT FOR SURFACE MOUNT DESIGN AND LAND PATTERN.

TOLERANCES UNLESS SPECIFIED DECIMAL ANGULAR		ID.
X± XX± XXX±		/w.IDT.cor
	10	NL/NLG72 0 x 10.0 . 50 mm Pito
	SIZE C	drawing no.
	DO NO	T SCALE DRA

2/2/16 00

CORRE



# **Ordering Information**

Part / Order Number	Shipping Package	Package	Temperature
9ZXL1950BKLF	Trays	72-pin VFQFPN	0 to +70°C
9ZXL1950BKLFT	Tape and Reel	72-pin VFQFPN	0 to +70°C

<sup>&</sup>quot;LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

### **Revision History**

Rev.	Issuer	Issue Date	Description	Page #
Α	RDW	3/11/2014	Moved to final.	
			Cleaned up output pin names to be DIFxx instead of DIF_xx	
			2. Updated electrical tables to new format	
В	RDW	3/7/2015	3. Updated ordering info to B rev along with Rev ID.	Various
			4. Updated termination schemes for driving LVDS.	
			5. Minor cleanup/reformatting of DS, including front page text.	
С	RDW	6/16/2015	Added landing pattern from POD	17
			1. Tightened O2O spec from 75 to 50ps	1,8
	RDW		2. Added epad (pin 73) to power connections table	2
		7/30/2015	3. Updated pin 73 pin name from "GND" to "epad"	4
D			4. Clarified SMBus operating frequency by removing the word "Maximum"	6
	אטח	7/30/2013	and updated the symbol from fMINSMB to fSMB	
			5. Tightened duty cycle distortion and additive cycle to cycle jitter specs	8
			6. Updated Rs from 7 to 7.5 ohms in Test Loads Table	9
			7. Replaced LVDS termination info with reference to AN891.	13
			Updated QPI references to QPI/UPI	
E	RDW	11/20/2015	2. Updated DIF_IN table to match PCI SIG specification, no silicon change	1,5
			2. Opuated Dif _invitable to match? Of Sid specification, no silicon change	
F	RDW	5/11/2017	Updated package outline drawings to latest version.	14-16

<sup>&</sup>quot;B" is the device revision designator (will not correlate with the datasheet revision).



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(Rev.1.0 Mar 2020)

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PI6C4931502-04LIE NB7L1008MNG NB7L14MN1G PI49FCT20807QE PI6C4931502-04LIEX ZL80002QAB1 PI6C4931504-04LIEX
PI6C10806BLEX ZL40226LDG1 ZL40219LDG1 8T73S208B-01NLGI SY75578LMG PI49FCT32805QEX PL133-27GC-R
CDCV304PWG4 MC10LVEP11DG MC10EP11DTG MC100LVEP11DG MC100E111FNG MC100EP11DTG NB6N11SMNG
NB7L14MMNG NB3N2304NZDTR2G NB6L11MMNG NB6L14MMNR2G NB6L611MNG PL123-02NGI-R NB3N111KMNR4G
ADCLK944BCPZ-R7 ZL40217LDG1 NB7LQ572MNG HMC940LC4BTR ADCLK946BCPZ-REEL7 ADCLK946BCPZ
ADCLK846BCPZ-REEL7